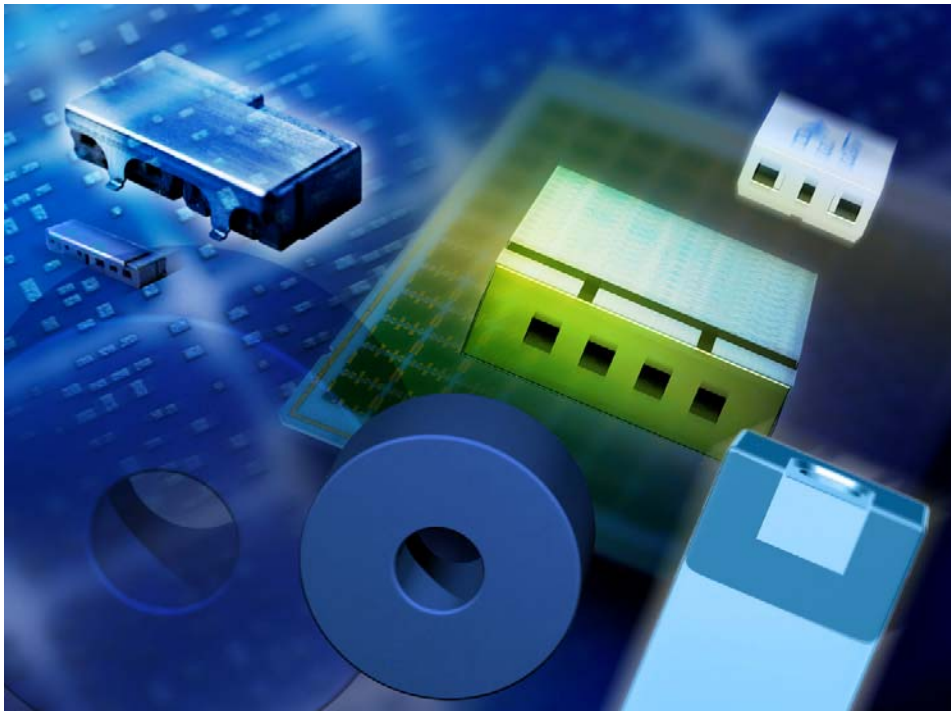


Data Sheet



Application

- RF filter for WLL (Wireless Local Loop)

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3\text{-CaTiO}_3$ ($\epsilon_r = 21 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

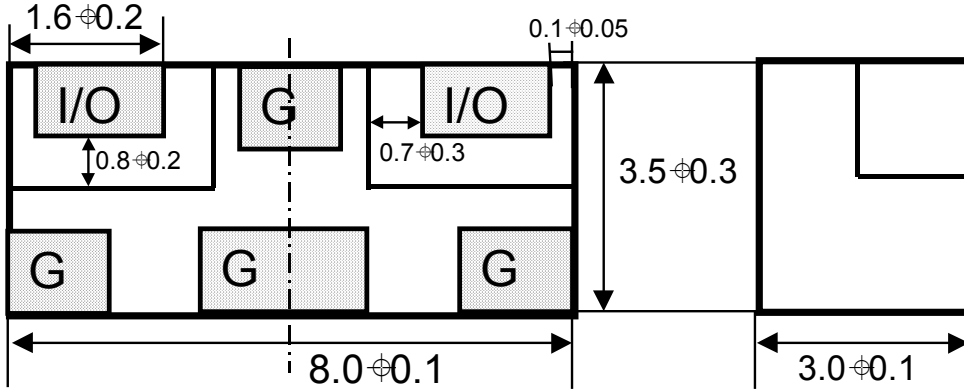
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Data Sheet

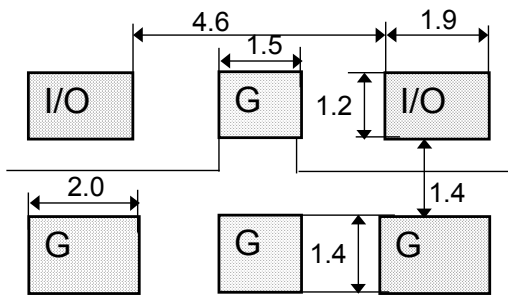
Component drawing



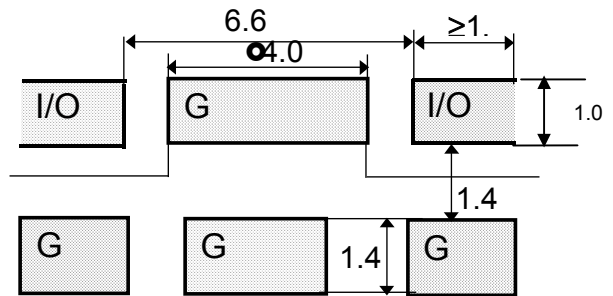
View from below onto the solder terminals and view from beside

Footprint

recommended



compatible footprint



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Data Sheet

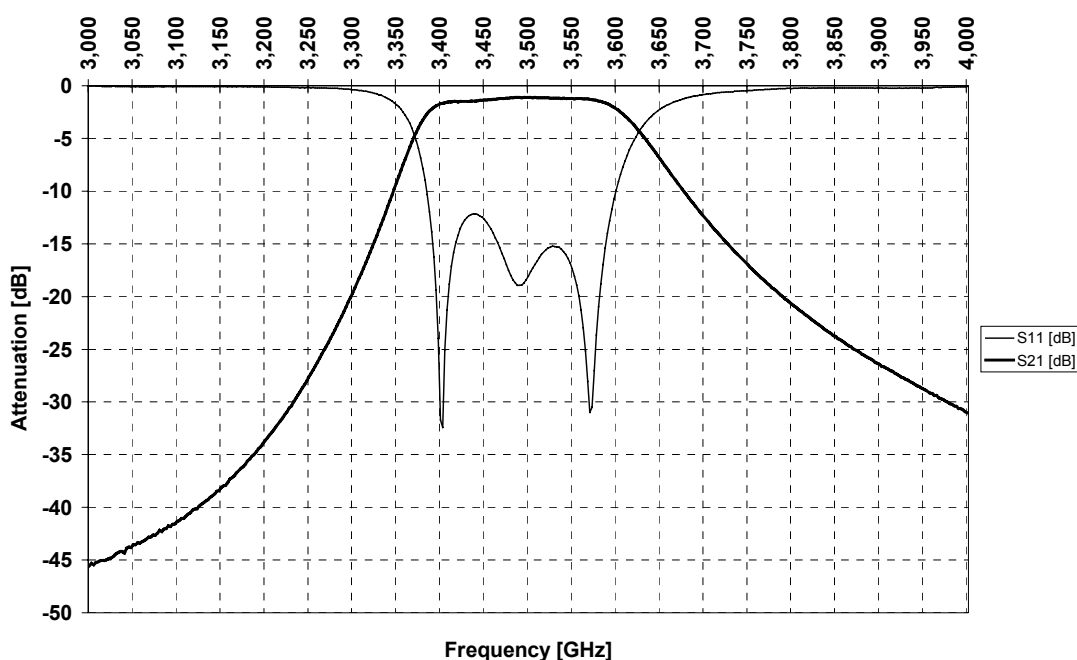
Characteristics

		min.	typ.	max.	
Center frequency	f_C	-	3500.0	-	MHz
Insertion loss	α_{IL}		1.2	1.8	dB
Passband	B	160			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.5	1.0	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	at DC to 2800 MHz at 2800 to 3240 MHz at 3900 to 5000 MHz at 5000 to 7200 MHz	α	40	45	dB
			26		dB
			25		dB
			20		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / + 85	°C

Typical passband characteristic



Data Sheet

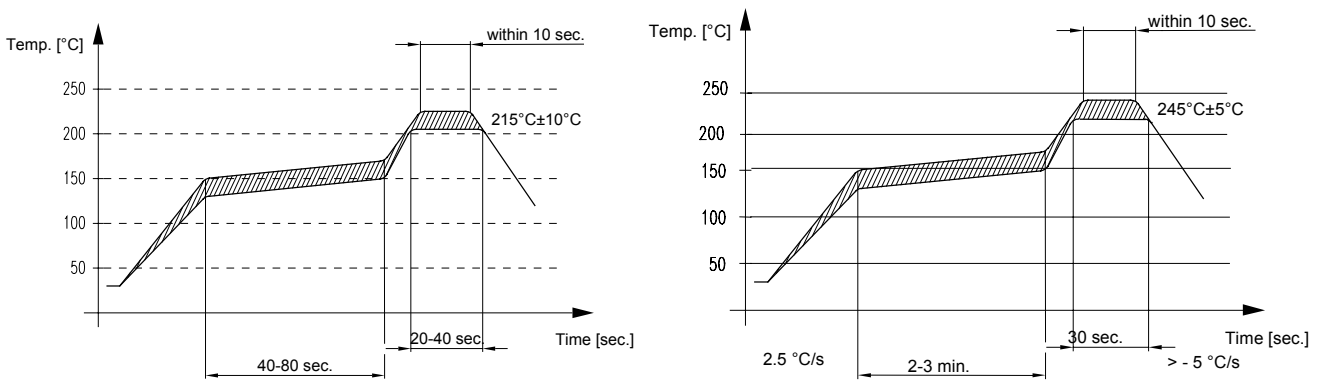
Processing information

- Wettability acc to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

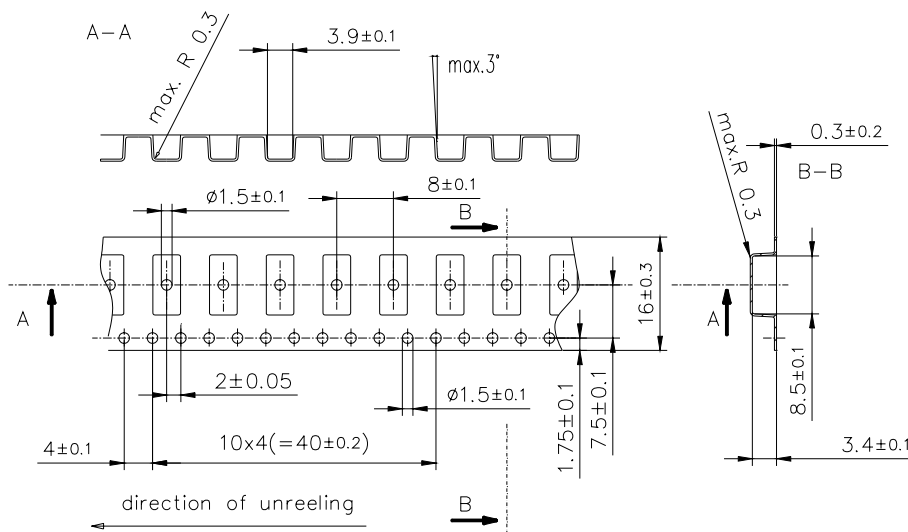
	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	$^{\circ}\text{C}$ $^{\circ}\text{C}$

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 2000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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